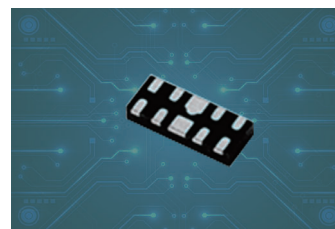


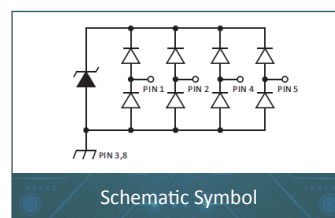
## 1. FEATURES

- 30W Peak Pulse Power per Line ( $t_p=8/20\mu s$ )
- Protects four I/O lines
- Operating voltage: 5.0V
- Ultra Low Capacitance: 0.4pF typical (I/O to GND)
- Weight: 8.0mg



## 2. APPLICATIONS

- USB2.0, USB3.0, Ethernet
- HDMI2.0, Displayport 1.3, eSATA
- Unified Display Interface
- Digital Visual Interface
- High Speed Serial Interface



## 3. IEC COMPATIBILITY

- IEC61000-4-2 (ESD)  $\pm 15kV$  (air),  $\pm 8kV$  (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 3A (8/20us)

## 4. THERMAL CONSIDERATIONS

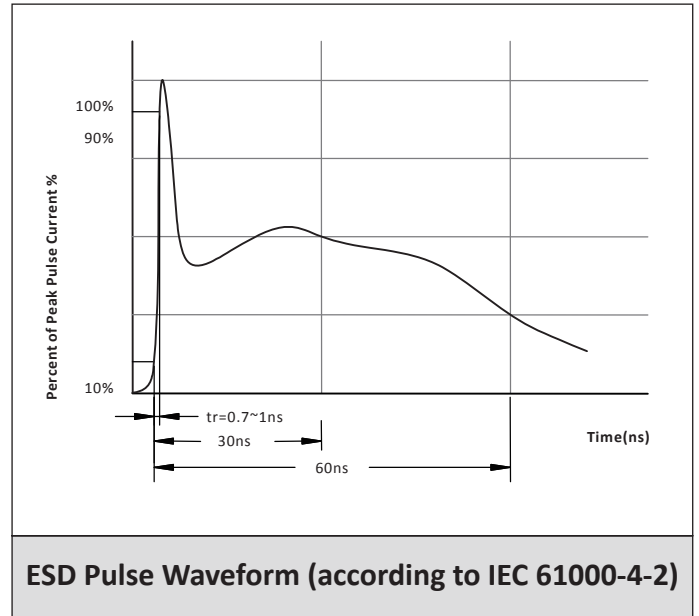
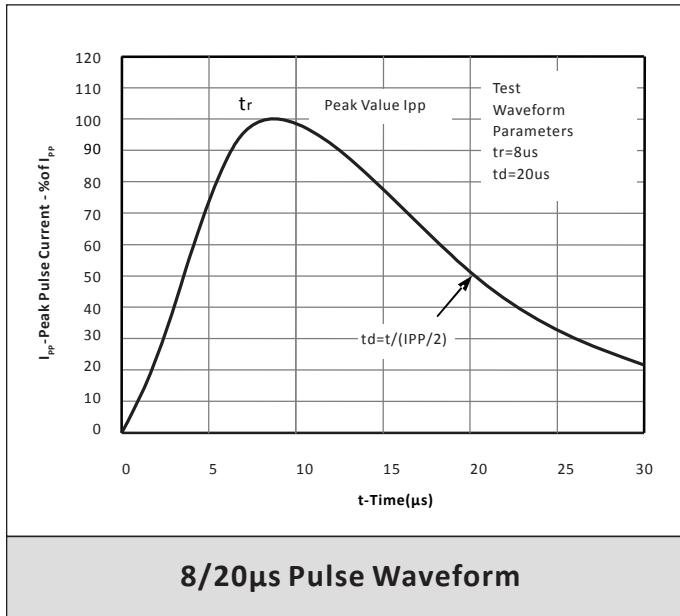
Symbol	Parameter	Value	Unit
$P_{pp}$	Peak Pulse Power ( $t_p=8/20\mu s$ waveform)	30	Watts
$T_J$	Operating Temperature Range	-55 to +150	$^{\circ}C$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^{\circ}C$

## 5. ELECTRICAL CHARACTERISTICS

Part Number	$V_{RWM}$	$V_{BR}$	$I_T$	$V_C$		$I_R$	$C_j$ I/O-I/O	$C_j$ I/O-I/GND
	Max.(V)	Min.(V)	(mA)	Max.(V)	@A	Max.(uA)	Typ.(pF)	Typ.(pF)
SEULC0524PA	5.0	6.0	1.0	11.0	3.0	0.5	0.2	0.4

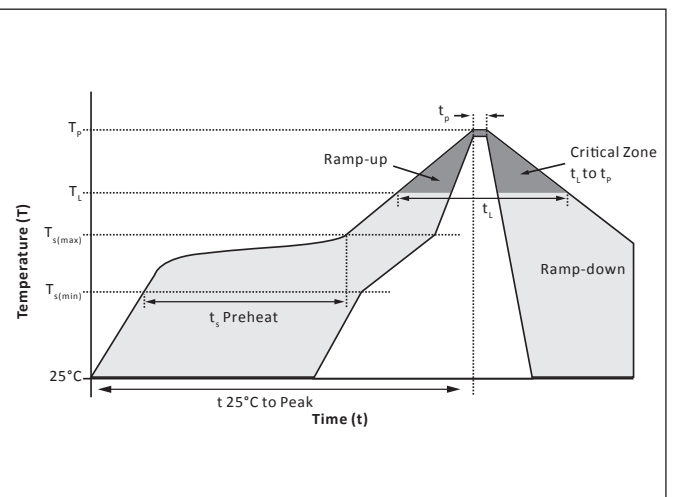


## 6. CHARACTERISTIC CURVES



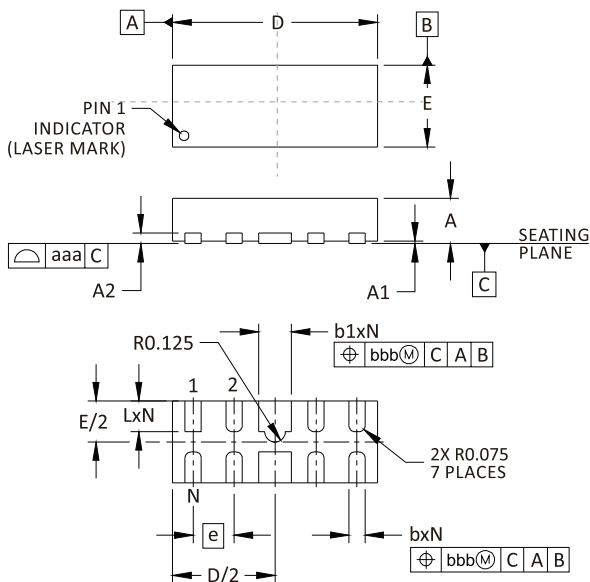
## 7. SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C



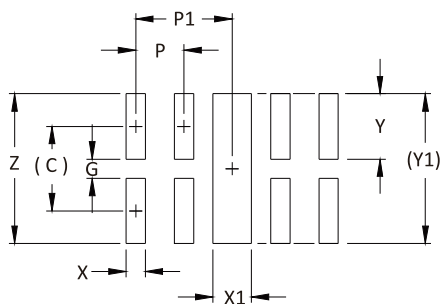
## 8. DFN2510P10 PACKAGE INFORMATION

DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.40	0.65	0.016	0.026
A1	0	0.05	0	0.002
A2	(0.13)		(0.005)	
b	0.15	0.25	0.006	0.010
b1	0.35	0.45	0.014	0.018
D	2.40	2.60	0.094	0.102
E	0.90	1.10	0.035	0.043
e	0.50BSC		0.020BSC	
L	0.30	0.45	0.012	0.018
N	8		8	
aaa	0.08		0.003	
bbb	0.10		0.004	



## 9. RECOMMENDED PAD LAYOUT DIMENSIONS

DIM	Millimeters	Inches
	Nominal	Nominal
C	0.87	0.034
G	0.20	0.008
P	0.50	0.020
P1	1.00	0.039
X	0.20	0.008
X1	0.40	0.016
Y	0.68	0.027
Y1	1.55	0.061
Z	1.55	0.061



## 10. ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SEULC0524PA	DFN2510P10	3000PCS	7"



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